

ABSOLUTE MAXIMUM RATING (T _A =25°C Unless Otherwise Specified)			
Parameter	Symbol	Rating	Units
Power Dissipation Derate linearly from 25°C	P _D	105 -1.14	mW mW/°C
Continuous Forward Current (MV5374C=20 mA)	I _F	35	mA
Peak Forward Current - (μsec pulse 0.3% duty cycle) (MV5474C=90 mA) (MV5374C=60 mA)	I _{FM}	35	mA
Reverse Voltage (I _R = 100 μA)	V _R	5	V
Lead Soldering Time at 260°C (See Note 1)	T _{SOL}	5	sec
Operating Temperature	T _{OPR}	-55 to +100	°C
Storage Temperature	T _{STG}	-55 to +100	°C

ELECTRICAL / OPTICAL CHARACTERISTICS (T _A =25°C)							
Part Number	Symbol	MV5074C	MV5075C	MV5374C	MV5474C	MV5774C	Condition
Luminous Intensity (mcd) Minimum Typical	I _V	0.7 2.5	0.6 1.5	1.5 9.0	1.2 9.0	1.5 9.0	I _F = 20mA
Forward Voltage (V) Typical Maximum	V _F	1.6 2.0	1.6 2.0	2.1 3.0	2.2 3.0	2.0 3.0	I _F = 20mA
Spectral Line Half Width (nm)		20	20	35	35	45	I _F = 20mA
Peak Wavelength (nm)	λ _p	660	660	585	565	635	I _F = 20mA
Reverse Current (μA) Maximum		100	100	100	100	100	V _R = 5.0V
Viewing Angle (Total) (°)	2θ 1/2	70	90	90	90	90	See Fig. 3

- The leads of the device were immersed in molten solder at 260°C, to a point 1/16 inch (1.6 mm) from the body of the device per MIL-S-750, with a dwell time of 5 seconds.

TYPICAL PERFORMANCE CURVES ($T_A = 25^\circ\text{C}$)

Fig. 1 Forward Current vs. Forward Voltage

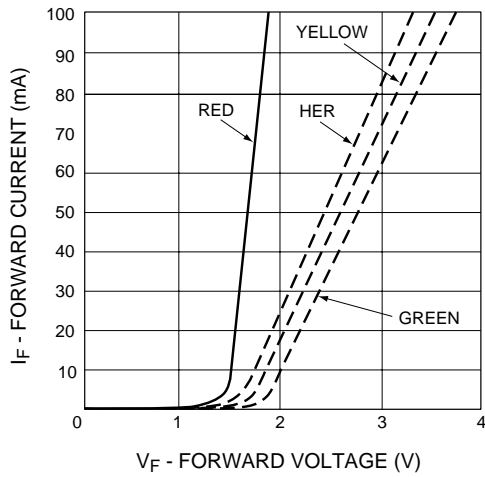


Fig. 2 Luminous Intensity vs. Forward Current

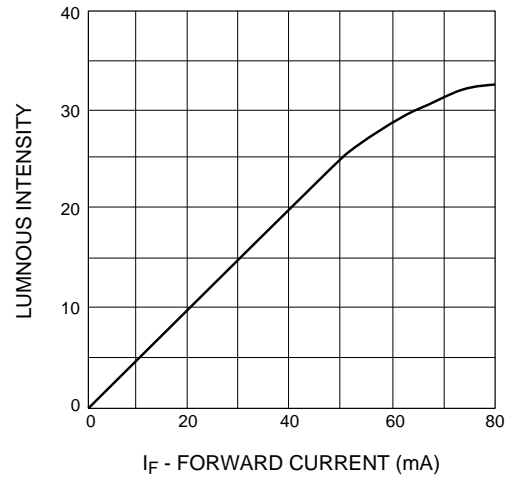


Fig. 3 Spatial Distribution

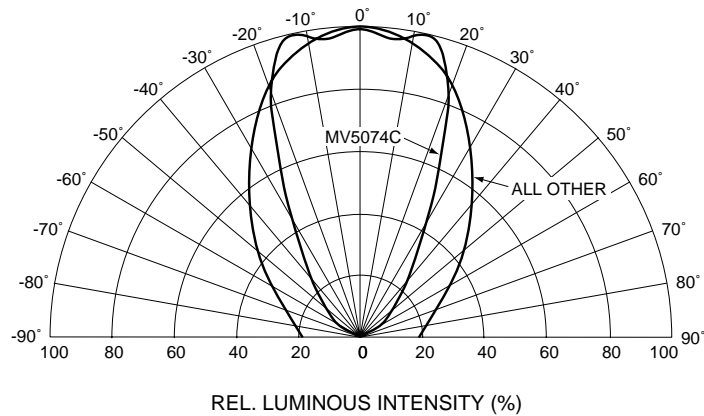
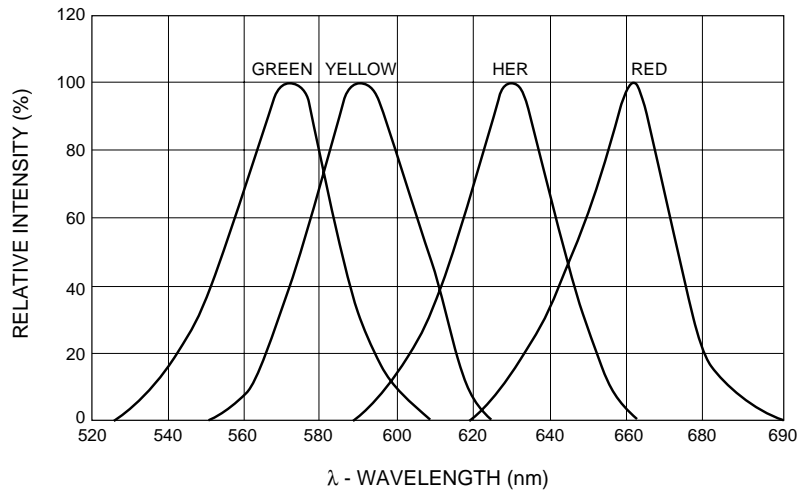


Fig. 4 Relative Intensity vs. Peak Wavelength



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